

Abstract

To satisfactorily apply a protective tape to a bump wafer, an application apparatus (1) for applying a protective tape (PT) to a wafer (W) includes: an application table (60) configured to support the wafer (W); a tape holding body (30) capable of holding the protective tape (PT) and configured to supply the protective tape (PT) held by the tape holding body (30) onto the wafer (W); and a pressing member (62) configured to press the protective tape (PT) from above. The pressing member (62) includes a protective layer outer periphery retainer (620) configured to press a peripheral portion of a protective layer (PL), which is laminated on the protective tape (PT) and has an outer diameter smaller than an outer diameter of the wafer (W), to apply the protective tape (PT) to the wafer (W).